

10/070000

FILED UNDER 35 U.S.C. 871

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10070000	FILING DATE 11/27/2002	CLASS 205	SUBCLASS 21	GAU 1741	EXAMINER Wong
----------------------	---------------------------	--------------	----------------	-------------	------------------

**APPLICANTS: Hu Jung-Chih; Gau Wu-Chun; Chang Ting-Chang; Feng Ming-Shiann; Cheng Chun-Lin; Lin You-Shin; Li Ying-Hao; Chen Lih-Juann;

**CONTINUING DATA VERIFIED:

This application is a 371 of PCT/EP00/08312 08/25/2000

** FOREIGN APPLICATIONS VERIFIED:
GERMANY 199 41 605.2 09/01/1999

BEST AVAILABLE COPY

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no
Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO MERCK 2395
TITLE : Galvanizing solution for the galvanic deposition of copper		
U.S.DEP.T. OF COMM/PAT. & TM-PTO-435L(Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims Print Claim for O.G	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.
TERMINAL DISCLAIMER		Print Fig.	
PREPARED FOR ISSUE		Application Examiner	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: DISK (CRF) CD-ROM
(Attached in pocket on right inside flap)